

CS5566

±2.5 V / 5 V, 5 kSps, 24-bit ΔΣ ADC

Features

- Differential Analog Input
- □ On-chip Buffers for High Input Impedance
- $\Box \quad Conversion Time = 200 \ \mu S$
- □ Settles in One Conversion
- □ Linearity Error = 0.0005%
- □ Signal-to-Noise = 110 dB
- 24 Bits, No Missing Codes
- □ Simple three/four-wire serial interface
- Dever Supply Configurations:
 - Analog: +5V/GND; IO: +1.8V to +3.3V
 - Analog: ±2.5V; IO: +1.8V to +3.3V
- Dever Consumption: 20 mW @ 5 kSps

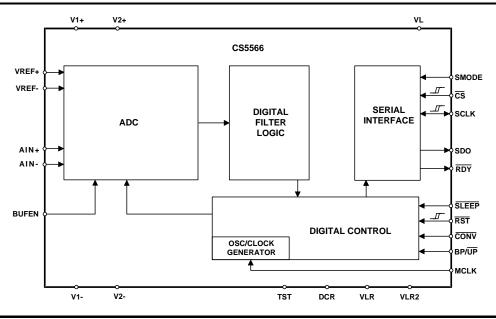
General Description

The CS5566 is a single-channel, 24-bit analog-to-digital converter capable of 5 kSps conversion rate. The input accepts a fully differential analog input signal. On-chip buffers provide high input impedance for both the AIN inputs and the VREF+ input. This significantly reduces the drive requirements of signal sources and reduces errors due to source impedances. The CS5566 is a delta-sigma converter capable of switching multiple input channels at a high rate with no loss in throughput. The ADC uses a low-latency digital filter architecture. The filter is designed for fast settling and settles to full accuracy in one conversion. The converter's 24-bit data output is in serial form, with the serial port acting as either a master or a slave. The converter is designed to support bipolar, ground-referenced signals when operated from $\pm 2.5V$ analog supplies.

The converter can operate from an analog supply of 0-5V or from $\pm 2.5V$. The digital interface supports standard logic operating from 1.8, 2.5, or 3.3 V.

ORDERING INFORMATION:

See Ordering Information on page 30.



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1. CHARACTERISTICS AND SPECIFICATIONS

- Min / Max characteristics and specifications are guaranteed over the specified operating conditions.
- Typical characteristics and specifications are measured at nominal supply voltages and T_A = 25°C.
- VLR = 0 V. All voltages with respect to 0 V.

ANALOG CHARACTERISTICS $T_A = -40$ to +85 °C; V1+ = V2+ = +2.5 V, $\pm 5\%$; V1- = V2- = -2.5 V, $\pm 5\%$; VL - VLR = 3.3 V, $\pm 5\%$; VREF = (VREF+) - (VREF-) = 4.096V; MCLK = 8 MHz; SMODE = VL. BUFEN = V1+ unless otherwise stated. Connected per Figure 8. Bipolar mode unless otherwise stated.

Parameter		Min	Тур	Max	Unit
Accuracy					•
Linearity Error		-	0.0005	-	±%FS
Differential Linearity Error	(Note 1)	-	±0.1	-	LSB ₂₄
Positive Full-scale Error		-	1.0	-	%FS
Negative Full-scale Error		-	1.0	-	%FS
Full-scale Drift	(Note 2)	-	1	-	PPM / °C
Bipolar Offset	(Note 2)	-	±500	-	LSB ₂₄
Bipolar Offset Drift	(Note 2)	-	1	-	LSB / °C
Noise		-	9.5	I	μVrms
Dynamic Performance					
Peak Harmonic or Spurious Noise	200 Hz, -0.5 dB Input	-	-115	-	dB
Total Harmonic Distortion	200 Hz, -0.5 dB Input	-	-110	-100	dB
Signal-to-Noise		108	110	-	dB
S/(N + D) Ratio	-0.5 dB Input, 200 Hz -60 dB Input, 200 Hz	-	109 50	-	dB dB
-3 dB Input Bandwidth	(Note 3)	-	21	-	kHz
Analog Input					
Analog Input Range (Differential)	Unipolar Bipolar		0 to +VRE ±VREF	F	V V
Input Capacitance		-	10	-	pF
CVF Current (Note 4)	AIN Buffer On (BUFEN = V+) AIN Buffer Off (BUFEN = V-)	-	600 130	-	nA μA
Common Mode Rejection Ratio (DC to 2 kH	łz)	-100	-110	-	dB

1. No missing codes is guaranteed at 24 bits resolution over the specified temperature range.

2. One LSB is equivalent to (2 x VREF) ÷ 2²⁴ or (2 x 4.096) ÷ 16,777,216 = 488 nV.

3. Scales with MCLK.

4. Measured using an input signal of 1 V DC.



ANALOG CHARACTERISTICS (CONTINUED) $T_A = -40$ to +85 °C; V1+ = V2+ = +2.5 V, $\pm 5\%$; V1- = V2- = -2.5 V, $\pm 5\%$; VL - VLR = 3.3 V, $\pm 5\%$; VREF = (VREF+) - (VREF-) = 4.096V; MCLK = 8 MHz; SMODE = VL.; BUFEN = V1+ unless otherwise stated. Connected per Figure 8.

Para	neter		Min	Тур	Max	Unit
Voltage Reference Input						
Voltage Reference Input Range (VREF+) – (VREF-)		(Note 5)	2.4	4.096	4.2	V
Input Capacitance			-	10	-	pF
CVF Current	VREF+ Buffer On (BU VREF+ Buffer Off (BL	,	- -	3 1 1		μA mA mA
Power Supplies						
Average DC Power Supply Curre	nts (Note 6)	I _{V1} I _{V2} I _{VL}	- -	- - -	5 0.6 0.4	mA mA mA
Peak DC Power Supply Currents	(Note 6)	I _{V1} I _{V2} I _{VL}	-	- - -	9 1.2 280	mA mA μA
Average Power Consumption	\	Buffers On Buffers Off LEEP = 0)	- - -	20 15 6	- - -	mW mW mW
Power Supply Rejection		+ Supplies - Supplies	75 75	85 85	-	dB dB

5. For optimum performance, VREF+ should always be less than (V+) - 0.2 volts to prevent saturation of the VREF+ input buffer.

6. Specification is for MCLK = 8MHz and 5 kSps conversion rate. MCLK frequency and conversion rate affect power consumption. See Section 3.2 Power Consumption for more details.

7. Tested with 100 mVP-P on any supply up to 2 kHz. V1+ and V2+ supplies at the same voltage potential, V1- and V2- supplies at the same voltage potential.

SWITCHING CHARACTERISTICS

 $T_A = -40$ to +85 °C; V1+ = V2+ = +2.5 V, ±5%; V1- = V2- = -2.5 V, ±5%;

VL - VLR = 3.3 V, ±5%, 2.5 V, ±5%, or 1.8 V, ±5%

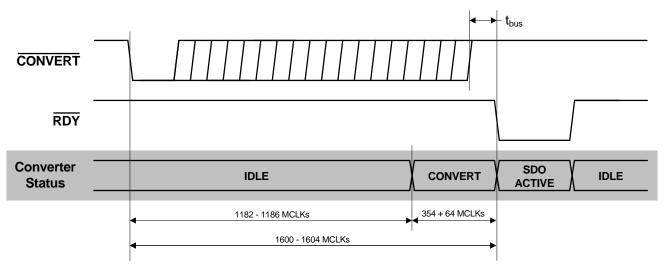
Input levels: Logic 0 = 0V Low; Logic 1 = VD + = High; CL = 15 pF.

	Parameter	Symbol	Min	Тур	Max	Unit
Master Clock Frequency	/ Internal Oscillator External Clock	XIN f _{clk}	6 0.5	7 8	8 8.1	MHz MHz
Master Clock Duty Cycle	9		40	-	60	%
Reset						
RST Low Time		t _{res}	1	-	-	μs
RST rising to RDY falling	g Internal Oscillator External Clock	t _{wup}	-	240 3084	-	µs MCLKs
Conversion						
CONV Pulse Width		t _{cpw}	4	-	-	MCLKs
BP/UP setup to CONV f	alling (Note 8)	t _{scn}	0	-	-	ns
CONV low to start of cor	nversion	t _{scn}	-	1182	1186	MCLKs
Perform Single Convers	ion (CONV high before RDY falling)	t _{bus}	20	-	-	MCLKs
Conversion Time	(Note 9) Start of Conversion to RDY falling	t _{buh}	-	-	1604	MCLKs
	LEEP low to low-power state LEEP high to device active (Note 10)	t _{con} t _{con}	-	50 3083	-	µs MCLKs

8. BP/UP can be changed coincident CONV falling. BP/UP must remain stable until RDY falls.

BLOONV is held low continuously, conversions occur every 1600 MCLK cycles. If RDY is tied to CONV, conversions will occur every 1602 MCLKs. If CONV is operated asynchronously to MCLK, a conversion may take up to 1604 MCLKs. RDY falls at the end of conversion.

10. RDY will fall when the device is fully operational when coming out of sleep mode.





SWITCHING CHARACTERISTICS (CONTINUED)

 $T_A = -40$ to +85 °C; V1+ = V2+ = +2.5 V, ±5%; V1- = V2- = -2.5 V, ±5%;

VL - VLR = 3.3 V, ±5%, 2.5 V, ±5%, or 1.8 V, ±5%

Input levels: Logic 0 = 0V Low; Logic 1 = VD+ = High; CL = 15 pF.

Parameter		Symbol	Min	Тур	Max	Unit
Serial Port Timing in SSC Mode (SM	IODE = VL)					
RDY falling to MSB stable		t ₁	-	-2	-	MCLKs
Data hold time after SCLK rising		t ₂	-	10	-	ns
Serial Clock (Out) (Note 11, 12)	Pulse Width (low) Pulse Width (high)	U U	100 100	-	-	ns ns
RDY rising after last SCLK rising		t ₅	-	8	-	MCLKs

11. SDO and SCLK will be high impedance when \overline{CS} is high. In some systems it may require a pull-down resistor.

12. SCLK = MCLK/2.

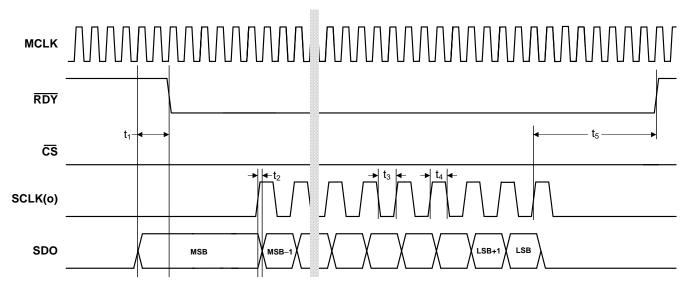


Figure 2. SSC Mode - Read Timing, CS remaining low (Not to Scale)

SWITCHING CHARACTERISTICS (CONTINUED)

 $T_A = -40$ to +85 °C; V1+ = V2+ = +2.5 V, ±5%; V1- = V2- = -2.5 V, ±5%;

VL - VLR = 3.3 V, ±5%, 2.5 V, ±5%, or 1.8 V, ±5%

Input levels: Logic 0 = 0V Low; Logic 1 = VD+ = High; CL = 15 pF.

Parameter	Symbol	Min	Тур	Max	Unit					
Serial Port Timing in SSC Mode (SMODE = VL)										
Data hold time after SCLK rising	t ₇	-	10	-	ns					
Serial Clock (Out)Pulse Wi(Note 13, 14)Pulse Wid		100 100	-	-	ns ns					
RDY rising after last SCLK rising	t ₁₀	-	8	-	MCLKs					
CS falling to MSB stable	t ₁₁	-	10	-	ns					
First SCLK rising after CS falling	t ₁₂	-	8	-	MCLKs					
CS hold time (low) after SCLK rising	t ₁₃	10	-	-	ns					
SCLK, SDO tri-state after \overline{CS} rising	t ₁₄	-	5	-	ns					

13. SDO and SCLK will be high impedance when $\overline{\text{CS}}$ is high. In some systems SCLK and SDO may require pull-down resistors.

14. SCLK = MCLK/2.

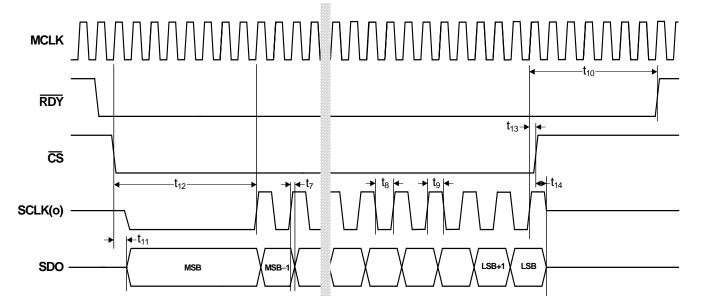


Figure 3. SSC Mode - Read Timing, CS falling after RDY falls (Not to Scale)

SWITCHING CHARACTERISTICS (CONTINUED)

 $T_A = -40$ to +85 °C; V1+ = V2+ = +2.5 V, ±5%; V1- = V2- = -2.5 V, ±5%;

VL - VLR = 3.3 V, ±5%, 2.5 V, ±5%, or 1.8 V, ±5%

Input levels: Logic 0 = 0V Low; Logic 1 = VD+ = High; CL = 15 pF.

Parameter	Symbol	Min	Тур	Max	Unit				
Serial Port Timing in SEC Mode (SMODE = VLR)									
SCLK(in) Pulse Width (High)	-	30	-	-	ns				
SCLK(in) Pulse Width (Low)	-	30	-	-	ns				
CS hold time (high) after RDY falling	t ₁₅	10	-	-	ns				
CS hold time (high) after SCLK rising	t ₁₆	10	-	-	ns				
CS low to SDO out of Hi-Z (Note 15)	t ₁₇	-	10	-	ns				
Data hold time after SCLK rising	t ₁₈	-	10	-	ns				
Data setup time before SCLK rising	t ₁₉	10	-	-	ns				
CS hold time (low) after SCLK rising	t ₂₀	10	-	1 SCLK-10	ns				
RDY rising after SCLK falling	t ₂₁	-	10	-	ns				

15. SDO will be high impedance when \overline{CS} is high. In some systems SDO may require a pull-down resistor.

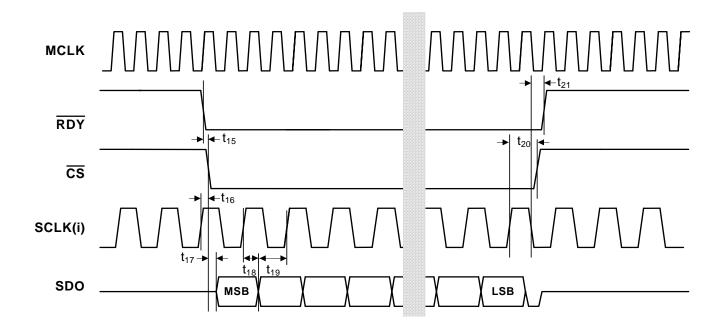


Figure 4. SEC Mode - Continuous SCLK Read Timing (Not to Scale)



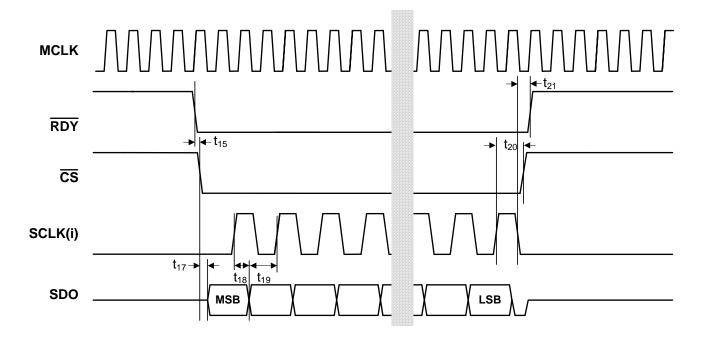


Figure 5. SEC Mode - Discontinuous SCLK Read Timing (Not to Scale)

DIGITAL CHARACTERISTICS

 T_A = TMIN to TMAX; VL = 3.3V, ±5% or VL = 2.5V, ±5% or 1.8V, ±5%; VLR = 0V

Parameter	Symbol	Min	Тур	Max	Unit
Input Leakage Current	l _{in}	-	-	2	μA
Digital Input Pin Capacitance	C _{in}	-	3	-	pF
Digital Output Pin Capacitance	C _{out}	-	3	-	pF

DIGITAL FILTER CHARACTERISTICS

 T_A = TMIN to TMAX; VL = 3.3V, ±5% or VL = 2.5V, ±5% or 1.8V, ±5%; VLR = 0V

Parameter	Symbol	Min	Тур	Max	Unit
Group Delay (Note 16)	-	-	160	-	MCLKs

16. See Figure 4 to understand conversion timing. The 160 MCLK group delay occurs during the 354 MCLK high-power period of a conversion cycle. See Section 3.2 Power Consumption for more detail.



GUARANTEED LOGIC LEVELS

 $T_A = -40$ to +85 °C; V1+ = V2+ = +2.5 V, ±5%; V1- = V2- = -2.5 V, ±5%;

VL - VLR = 3.3 V, \pm 5%, 2.5 V, \pm 5%, or 1.8 V, \pm 5% Input levels: Logic 0 = 0V Low; Logic 1 = VD+ = High; CL = 15 pF.

			Guai	ranteed L	imits]	
Parameter	Sym	VL	Min	Тур	Max	Unit	Conditions
_ogic Inputs							
		3.3	1.9				
Minimum High-level Input Voltage:	V_{IH}	2.5	1.6			V	
		1.8	1.2				
		3.3			1.1		
Maximum Low-level Input Voltage:	V _{IL}	2.5			0.95	V	
		1.8			0.6		
_ogic Outputs							
		3.3	2.9				
Minimum High-level Output Voltage:	V _{OH}	2.5	2.1			V	I _{OH} = -2 mA
		1.8	1.65				
		3.3			0.36		
Maximum Low-level Output Voltage:	V _{OL}	2.5			0.36	V	I _{OH} = -2 mA
		1.8			0.44		



RECOMMENDED OPERATING CONDITIONS

(VLR = 0V, see Note 17)

Parameter	Symbol	Min	Тур	Max	Unit	
Single Analog Supply						
DC Power Supplies:	(Note 17)					
	V1+	V1+	4.75	5.0	5.25	V
	V2+	V2-	4.75	5.0	5.25	V
	V1-	V1+	-	0	-	V
	V2-	V2-	-	0	-	V
Dual Analog Supplies						
DC Power Supplies:	(Note 17)					
	V1+	V1+	+2.375	+2.5	+2.625	V
	V2+	V2-	+2.375	+2.5	+2.625	V
	V1-	V1+	-2.375	-2.5	-2.625	V
	V2-	V2-	-2.375	-2.5	-2.625	V
Analog Reference Voltage	(Note 18) [VREF+] – [VREF-]	VREF	2.4	4.096	4.2	V

17. The logic supply can be any value VL - VLR = +1.71 to +3.465 volts as long as $VLR \ge V2$ - and $VL \le 3.465$ V.

18. The differential voltage reference magnitude is constrained by the V1+ or V1- supply magnitude.

ABSOLUTE MAXIMUM RATINGS

(VLR = 0V)

Param	Symbol	Min	Тур	Max	Unit	
DC Power Supplies:						
	[V1+] – [V1-] (Note 19)	-	0	-	5.5	V
	VL + [V1-] (Note 20)	-	0	-	6.1	V
Input Current, Any Pin Except Supplies (Note 21)		I _{IN}	-	-	±10	mA
Analog Input Voltage	(AIN and VREF pins)	V _{INA}	(V1-) – 0.3	-	(V1+) + 0.3	V
Digital Input Voltage		V _{IND}	VLR – 0.3	-	VL + 0.3	V
Storage Temperature		T _{stg}	-65	-	150	°C

Notes: 19. V1+ = V2+; V1- = V2-

20. V1- = V2-

21. Transient currents of up to 100 mA will not cause SCR latch-up.

WARNING:

Recommended Operating Conditions indicate limits to which the device is functionally operational. Absolute Maximum Ratings indicate limits beyond which permanent damage to the device may occur. The Absolute Maximum Ratings are stress ratings only and the device should not be operated at these limits. Operation at conditions beyond the Recommended Operating Conditions may affect device reliability, and functional operation beyond Recommended Operating Conditions is not implied. Performance specifications are intended for the conditions specified for each table in the Characteristics and Specifications section.



2. OVERVIEW

The CS5566 is a 24-bit analog-to-digital converter capable of 5 kSps conversion rate. The device is capable of switching multiple input channels at a high rate with no loss in throughput. The ADC uses a low-latency digital filter architecture. The filter is designed for fast settling and settles to full accuracy in one conversion.

The converter is a serial output device. The serial port can be configured to function as either a master or a slave.

The converter can operate from an analog supply of 5V or from $\pm 2.5V$. The digital interface supports standard logic operating from 1.8, 2.5, or 3.3 V.

The CS5566 converts at 5 kSps when operating from a 8 MHz input clock.

3. THEORY OF OPERATION

The CS5566 converter provides high-performance measurement of DC or AC signals. The converter can be used to perform single conversions or continuous conversions upon command. Each conversion is independent of previous conversions and can settle to full specified accuracy, even with a full-scale input voltage step. This is due to the converter architecture which uses a combination of a high-speed delta-sigma modulator and a low-latency filter architecture.

Once power is established to the converter, a reset must be performed. A reset initializes the internal converter logic.

If $\overline{\text{CONV}}$ is held low then the converter will convert continuously with $\overline{\text{RDY}}$ falling every 1600 MCLKs. This is equivalent to <u>5 kSps</u> if MCLK = 8.0 MHz. If $\overline{\text{CONV}}$ is tied to $\overline{\text{RDY}}$, a conversion will occur every 1602 MCLKs. If $\overline{\text{CONV}}$ is operated asynchronously to MCLK, it may take up to 1604 MCLKs from $\overline{\text{CONV}}$ falling to $\overline{\text{RDY}}$ falling.

Multiple converters can operate synchronously if they are driven by the same MCLK source and CONV to each converter falls on the same MCLK falling edge. Alternately, CONV can be held low and all devices are reset with RST rising on the same falling edge of MCLK.

The output coding of the conversion word is a function of the BP/UP pin.

The active-low SLEEP signal causes the device to enter a low-power state. When exiting sleep, the converter will take 3083 MCLK cycles before conversions can be performed. RST should remain inactive (high) when SLEEP is asserted (low).



3.1 Converter Operation

The converter should be reset after the power supplies and voltage reference are stable.

The CS5566 converts at 5 kSps when synchronously operated ($\overline{\text{CONV}} = \text{VLR}$) from a 8.0 MHz master clock. Conversion is initiated by taking $\overline{\text{CONV}}$ low. A conversion lasts 1600 master clock cycles, but if CONV is asynchronous to MCLK there may be an uncertainty of 0-4 MCLK cycles after CONV falls to when a conversion actually begins. This may extend the throughput to 1604 MCLKs

When the conversion is completed, the output word is placed into the serial port and $\overline{\text{RDY}}$ goes low. To convert continuously, CONV should be held low. In continuous conversion mode with CONV held low, a conversion is performed in 1600 MCLK cycles. Alternately $\overline{\text{RDY}}$ can be tied to $\overline{\text{CONV}}$ and a conversion will occur every 1602 MCLK cycles.

To perform only one conversion, CONV should return high at least 20 master clock cycles before RDY falls.

Once a conversion is completed and RDY falls, RDY will return high when all the bits of the data word are emptied from the serial port or if the conversion data is not read and CS is held low, RDY will go high two MCLK cycles before the end of conversion. RDY will fall at the end of the next conversion when new data is put into the port register.

See Section 3.11 Serial Port for information about reading conversion data.

Conversion performance can be affected by several factors. These include the choice of clock source for the chip, the timing of CONV, and the choice of the serial port mode.

The converter can be operated from an internal oscillator. This clock source has greater jitter than an external crystal-based clock. Jitter may not be an issue when measuring DC signals, or very-low-frequency AC signals, but can become an issue for higher frequency AC signals. For maximum performance when digitizing AC signals, a low-jitter MCLK should be used.

To maximize performance, the $\overline{\text{CONV}}$ pin should be held low in the continuous conversion state to perform multiple conversions, or $\overline{\text{CONV}}$ should occur synchronous to MCLK, falling when MCLK falls.

If the converter is operated at maximum throughput, the SSC serial port mode is less likely to cause interference to measurements as the SCLK output is synchronized to the MCLK. Alternately, any interference due to serial port clocking can also be minimized if data is read in the SEC serial port mode when a conversion is not in progress.



3.2 Power Consumption

The power consumption of the CS5566 converter is a function of the conversion rate. Figure 6 illustrates the typical power consumption of the converter when operating from either MCLK = 8 MHz or MCLK = 4 MHz. The rate at which conversions are performed directly affects the power consumption. When the converter is powered but not converting, it is in an idle state where its power consumption is about 11 mW. When the CONV signal goes low to start a conversion, the converter delays the actual start of conversion for 1182 to 1186 MCLK cycles, depending upon how CONV is controlled. The timing for the conversion sequence is shown in Figure 1 on page 6. After the 1182 - 1186 MCLK delay from when CONV goes low, the converter enters a higher-power state for 354 MCLK cycles and then returns to a lower-power state for 64 MCLK cycles, after which the RDY signal falls to indicate the completion of a conversion. Since the peak operating current for the converter occurs during the 354 MCLK, higher-power state, it is recommended that a large capacitor be used on the supply to the converter (as shown in Figures 9 and 10). This capacitor filters the peak current demand from the power supply. The average power consumption for the converter will depend upon the frequency of MCLK and the rate at which conversions are performed as illustrated in Figure 1 on page 6.

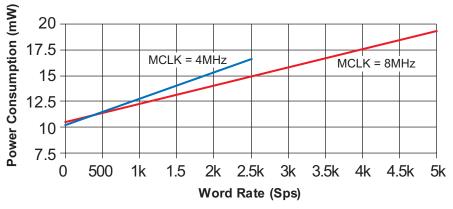


Figure 6. Power Consumption vs. Conversion Rate



3.3 Clock

The CS5566 can be operated from its internal oscillator or from an external master clock. The state of MCLK determines which clock source will be used. If MCLK is tied low, the internal oscillator will start and be used as the clock source for the converter. If an external CMOS-compatible clock is input into MCLK the converter will power down the internal oscillator and use the external clock. If the MCLK pin is held high, the internal oscillator will be held in the stopped state. The MCLK input can be held high to delete clock cycles to aid in operating multiple converters in different phase relationships.

The internal oscillator can be used if the signals to be measured are essentially DC. The internal oscillator exhibits jitter at about 500 picoseconds rms. If the CS5566 is used to digitize AC signals, an external low-jitter clock source should be used.

If the internal oscillator is used as the clock for the CS5566, the maximum conversion rate will be dictated by the oscillator frequency.

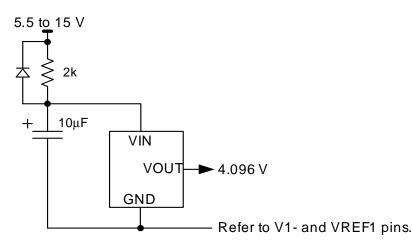
If driven from an external MCLK source, the fast rise and fall times of the MCLK signal can result in clock coupling from the internal bond wire of the IC to the analog input. Adding a 50 ohm resistor on the external MCLK source significantly reduces this effect.

3.4 Voltage Reference

The voltage reference for the CS5566 can range from 2.4 volts to 4.2 volts. A 4.096 volt reference is required to achieve the specified performance. Figure 8 and Figure 9 illustrate the connection of the voltage reference with either a single +5 V analog supply or with ± 2.5 V.

For optimum performance, the voltage reference device should be one that provides a capacitor connection to provide a means of noise filtering, or the output should include some type of bandwidth-limiting filter. Some 4.096 volt reference devices need only 5 volts total supply for operation and can be connected as shown in Figure 8 or Figure 9. The reference should have a local bypass capacitor and an appropriate output capacitor.

Some older 4.096 voltage reference designs require more headroom and must operate from an input voltage of 5.5 to 6.5 volts. If this type of voltage reference is used ensure that when power is applied to the system, the voltage reference rise time is slower than the rise time of the V1+ and V1- power supply voltage to the converter. An example circuit to slow the output startup time of the reference is illustrated in Figure 7.







3.5 Analog Input

The analog input of the converter is fully differential with a peak-to-peak input of 4.096 volts on each input. Therefore, the differential, peak-to-peak input is 8.192 volts. This is illustrated in Figure 8 and Figure 9. These diagrams also illustrate a differential buffer amplifier configuration for driving the CS5566.

The capacitors at the outputs of the amplifiers provide a charge reservoir for the dynamic current from the A/D inputs while the resistors isolate the dynamic current from the amplifier. The amplifiers can be powered from higher supplies than those used by the A/D but precautions should be taken to ensure that the opamp output voltage remains within the power supply limits of the A/D, especially under start-up conditions.

3.6 Output Coding Format

The reference voltage directly defines the input voltage range in both the unipolar and bipolar configurations. In the unipolar configuration (BP/UP low), the first code transition occurs 0.5 LSB above zero, and the final code transition occurs 1.5 LSBs below VREF. In the bipolar configuration (BP/UP high), the first code transition occurs 0.5 LSB above -VREF and the last transition occurs 1.5 LSBs below +VREF. See Table 1 for the output coding of the converter.

Bipolar Input Voltage	Two's Complement
>(VREF-1.5 LSB)	7F FF FF
	7F FF FF
VREF-1.5 LSB -	-
	7F FF FE
	00 00 00
-0.5 LSB -	- 1
	FF FF FF
	80 00 01
-VREF+0.5 LSB -	-
	80 00 00
<(-VREF+0.5 LSB)	80 00 00

Table 1. Output Coding, Two's Complement

NOTE: VREF = (VREF+) - (VREF-)

Table 2. Output Coding, Offset Binary

Unipolar Input Voltage	Offset Binary
>(VREF-1.5 LSB)	FF FF FF
VREF-1.5 LSB -	FF FF FF
	FF FF FE
(VREF/2)-0.5 LSB -	80 00 00
	7F FF FF
+0.5 LSB -	00 00 01
	00 00 00
<(+0.5 LSB)	00 00 00

NOTE: VREF = (VREF+) - (VREF-)



3.7 Typical Connection Diagrams

The following figure depicts the CS5566 powered from bipolar analog supplies, +2.5 V and - 2.5 V.

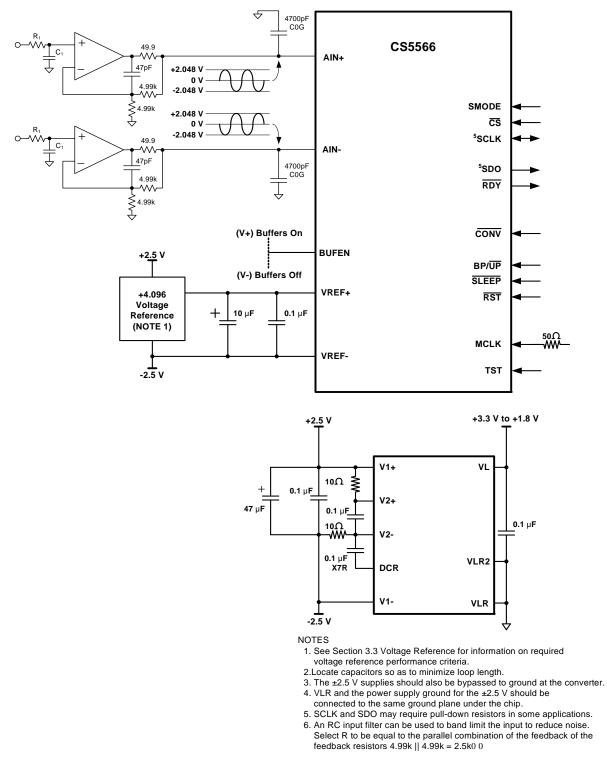


Figure 8. CS5566 Configured Using ±2.5V Analog Supplies

The following figure depicts the CS5566 device powered from a single 5V analog supply.

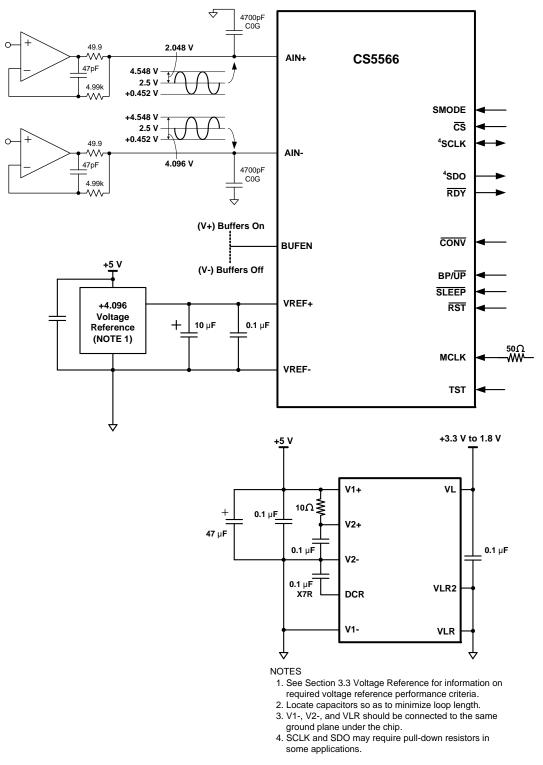


Figure 9. CS5566 Configured Using a Single 5V Analog Supply



3.8 AIN & VREF Sampling Structures

The CS5566 uses on-chip buffers on the AIN+, AIN-, and the VREF+ inputs. Buffers provide much higher input impedance and therefore reduce the amount of drive current required from an external source. This helps minimize errors.

The Buffer Enable (BUFEN) pin determines if the on-chip buffers are used or not. If the BUFEN pin is connected to the V1+ supply, the buffers will be enabled. If the BUFEN pin is connected to the V1- pin, the buffers are off. The converter will consume about 5 mW less power when the buffers are off, but the input impedances of AIN+, AIN- and VREF+ will be significantly less than with the buffers enabled.

3.9 Converter Performance

The CS5566 achieves excellent differential nonlinearity (DNL). Figure 10 illustrates the code widths on the typical scale of ± 1 LSB and on a zoomed scale of ± 0.2 LSB.

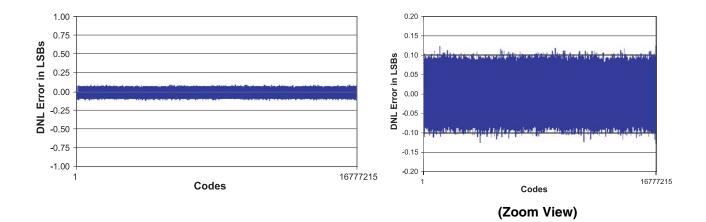


Figure 10. CS5566 DNL Plot



Figure 11 through Figure 16 illustrate the performance of the converter with various input signal magnitudes.

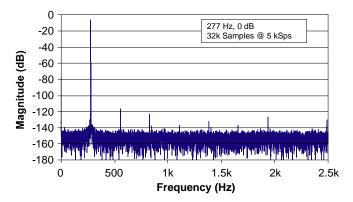
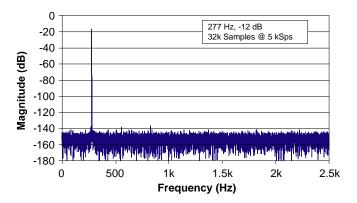
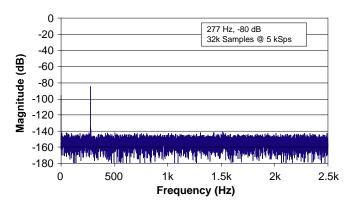


Figure 11. Spectral Performance, 0 dB









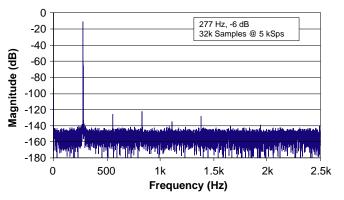
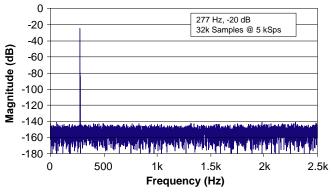


Figure 12. Spectral Performance, -6 dB





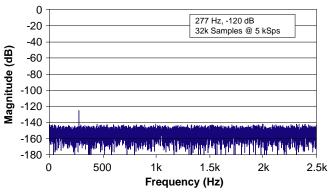


Figure 16. Spectral Performance, -120 dB

CS5566



Figure 16 illustrates the device with a small signal 1/1,000,000 of full scale. The signal input for Figure 16 is about 8.2 microvolts peak to peak, or about 17 codes peak to peak. Figure 17 illustrates the converter with a signal at about 2.6 microvolts peak to peak, or about 5 codes peak to peak. The CS5566 achieves superb performance with this small signal.

Figure 18 illustrates the noise floor of the converter from 0.1 Hz to 2.5 kHz. The plot is entirely free of spurious frequency content due to digital activity inside the chip.

Figure 19 illustrates a noise histogram of the converter constructed from 4096 samples.

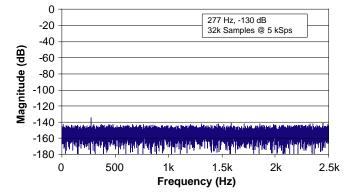


Figure 17. Spectral Performance, -130 dB

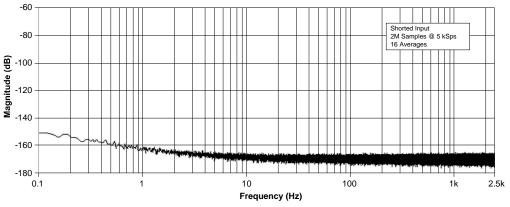


Figure 18. Spectral Plot of Noise with Shorted Input

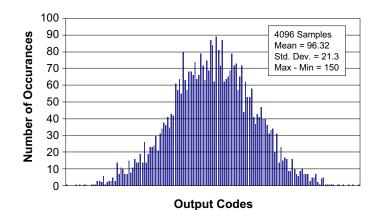
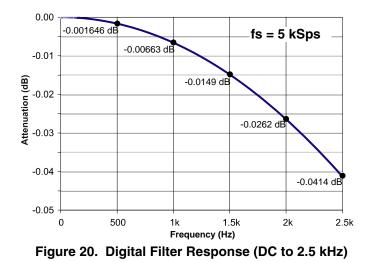


Figure 19. Noise Histogram (4096 Samples)



3.10 Digital Filter Characteristics

The digital filter is designed for fast settling, therefore it exhibits very little in-band attenuation. The filter attenuation is -0.0414 dB at 2.5 kHz when sampling at 5 kSps.





3.11 Serial Port

The serial port on the CS5566 can operate in two different modes: synchronous self clock (SSC) mode & synchronous external clock (SEC) mode. The serial port must be placed into the SEC mode if the offset and gain registers of the converter are to be read or written. The converter must be idle when reading or writing to the on-chip registers.

3.11.1 SSC Mode

If the SMODE pin is high (SMODE = VL), the serial port operates in the SSC (Synchronous Self Clock) mode. In the SSC mode the port shifts out conversion data words with SCLK as an output. SCLK is generated inside the converter from MCLK. Data is output from the SDO (Serial Data Output) pin. If CS is high, the SDO and SCLK pins will stay in a high-impedance state. If CS is low when RDY falls, the conversion data word will be output from SDO MSB first. Data is output on the rising edge of SCLK and should be latched into the external logic on the subsequent rising edge of SCLK. When all bits of the conversion word are output from the RDY signal will return to high.

3.11.2 SEC Mode

If the SMODE pin is low (SMODE = VLR), the serial <u>port</u> operates in the SEC (Synchronous External Clock mode). In this mode, the user usually monitors RDY. When RDY falls at the end of a conversion, the conversion data word is placed into the output data register in the serial port. CS is then activated low to enable data output. Note that CS can be held low continuously if it is not necessary to have the SDO output operate in the high impedance state. When CS is taken low (after RDY falls) the conversion data word is then shifted out of the SDO pin by driving the SCLK pin from system logic external to the converter. Data bits are advanced on rising edges of SCLK and latched by the subsequent rising edge of SCLK.

If \overline{CS} is held low continuously, the \overline{RDY} signal will fall at the end of a conversion and the conversion data will be placed into the serial port. If the user starts a read, the user will maintain control over the serial port until the port is empty. However, if SCLK is not toggled, the converter will overwrite the conversion data at the completion of the next conversion. If \overline{CS} is held low and no read is performed, \overline{RDY} will rise just prior to the end of the next conversion and then fall to signal that new data has been written into the serial port.



3.12 Power Supplies & Grounding

The CS5566 can be configured to operate with its analog supply operating from 5V, or with its analog supplies operating from $\pm 2.5V$. The digital interface supports digital logic operating from either 1.8V, 2.5V, or 3.3V.

Figure 8 on page 18 illustrates the device configured to operate from ± 2.5 V analog. Figure 9 on page 19 illustrates the device configured to operate from 5V analog. Note that the schematic indicates a 47 μ F capacitor between V1+ and V1-. This capacitor is necessary to reduce the peak current required from the power supply during conversion. See *Power Consumption* on page 16 for a more detailed discussion.

To maximize converter performance, the analog ground and the logic ground for the converter should be connected at the converter. In the dual analog supply configuration, the analog ground for the ± 2.5 V supplies should be connected to the VLR pin at the converter with the converter placed entirely over the analog ground plane.

In the single analog supply configuration (+5V), the ground for the +5V supply should be directly tied to the VLR pin of the converter with the converter placed entirely over the analog ground plane. Refer to Figure 9 on page 19.

3.13 Using the CS5566 in Multiplexing Applications

The actual conversion process inside the CS5566 begins 1182 MCLK cycles after the $\overline{\text{CONV}}$ signal is taken low. This would be over 147 microseconds when MCLK = 8 MHz. If the input channel of an external multiplexer is changed coincident with $\overline{\text{CONV}}$ going low, the 1182 MCLK delay should be more than an adequate time for settling. If there is an operational amplifier between the multiplexer and the converter, one should be certain that the amplifier can settle within the 1182 MCLK delay period. If not, the multiplexer er will need to be switched some time prior to $\overline{\text{CONV}}$ going low.

3.14 Synchronizing Multiple Converters

Many measurement systems have multiple converters that need to operate synchronously. The converters should all be driven from the same master clock. In this configuration, the converters will convert synchronously if the same CONV signal is used to drive all the converters, and CONV falls on a falling edge of MCLK. If CONV is held low continuously, reset (RST) can be used to synchronize multiple converters if RST is released on a falling edge of MCLK.



4. PIN DESCRIPTIONS

Chip Select	CS	24	RDY	Ready
Factory Test	TST 2	23		Serial Clock Input/Output
Serial Mode Select	SMODE 🖂 3	22	SDO	Serial Data Output
Differential Analog Input	AIN+ 🖂 4	21	U VL	Logic Interface Power
Differential Analog Input	AIN- 🖂 5	20	VLR	Logic Interface Return
Negative Power 1	V1- 🖂 6	19		Master Clock
Positive Power 1	V1+ 🖂 7	18	─ V2-	Negative Voltage 2
Buffer Enable	BUFEN 💳 8	17	□ V2+	Positive Voltage 2
Voltage Reference Input	VREF+ 9	16	DCR	Digital Core Regulator
Voltage Reference Input	VREF 10	15		Convert
Bipolar/Unipolar Select	BP/UP === 11	14	VLR2	Logic Interface Return
Sleep Mode Select	SLEEP 12	13	RST	Reset

CS – Chip Select, Pin 1

The Chip Select pin allows an external device to access the serial port. If SMODE = VL (SSC Mode) and \overline{CS} is held high, the SDO output and the SCLK output will be held in a high-impedance output state.

TST – Factory Test, Pin 2

Factory test only. Connect to VLR.

SMODE – Serial Mode Select, Pin 3

The serial interface mode pin (SMODE) dictates whether the serial port behaves as a master or slave interface. If SMODE is tied high (to VL), the port will operate in the Synchronous Self-Clocking (SSC) mode. In SSC mode, the port acts as a master in which the converter outputs both the SDO and SCLK signals. If SMODE is tied low (to VLR), the port will operate in the Synchronous External Clocking (SEC) mode. In SEC mode. In SEC mode, the port acts as a slave in which the external logic or microcontroller generates the SCLK used to output the conversion data word from the SDO pin.

AIN+, AIN- - Differential Analog Input, Pin 4, 5

AIN+ and AIN- are differential inputs for the converter.

V1- - Negative Power 1, Pin 6

The V1- and V2- pins provide a negative supply voltage to the core circuitry of the chip. These two pins should be decoupled as shown in the application block diagrams. V1- and V2- should be supplied from the same source voltage. For single-supply operation, these two voltages are nominally 0 V (Ground). For dual-supply operation, they are nominally -2.5 V.

V1+ - Positive Power 1, Pin 7

The V1+ and V2+ pins provide a positive supply voltage to the core circuitry of the chip. These two pins should be decoupled as shown in the application block diagrams. V1+ and V2+ should be supplied from the same source voltage. For single supply-operation, these two voltages are nominally +5 V. For dual-supply operation, they are nominally +2.5 V.

BUFEN – Buffer Enable, Pin 8

Buffers on input pins AIN+ and AIN- are enabled if BUFEN is connected to V1+ and disabled if connected to V1-.

VREF+, VREF- – Voltage Reference Input, Pin 9, 10

A differential voltage reference input on these pins functions as the voltage reference for the converter. The voltage between these pins can range between 2.4 volts and 4.2 volts, with 4.096 volts being the nominal reference voltage value.

BP/UP – Bipolar/Unipolar Select, Pin 11

The BP/ \overline{UP} pin determines the span and the output coding of the converter. When set high to select BP (bipolar), the input span of the converter is -4.096 volts to +4.096 volts fully differential (assuming the voltage reference is 4.096 volts) and output data is coded in two's complement format. When set low to select \overline{UP} (unipolar), the input span is 0 to +4.096 fully differential and the output data is coded in binary format.

SLEEP – Sleep Mode Select, Pin 12

When taken low, the SLEEP pin will cause the converter to enter into a low-power state. SLEEP will stop the internal oscillator and power down all internal analog circuitry.

RST - Reset, Pin 13

Reset is necessary after power is initially applied to the converter. When the RST input is taken low, the logic in the converter will be reset. When RST is released to go high, certain portions of the analog circuitry are started. RDY falls when reset is complete.

CONV – Convert, Pin 15

The CONV pin initiates a conversion cycle if taken low, unless a previous conversion is in progress. When the conversion cycle is completed, the conversion word is output to the serial port register and the RDY signal goes low. If CONV is held low and remains low when RDY falls, another conversion cycle will be started.

DCR – Digital Core Regulator, Pin 16

DCR is the output of the on-chip regulator for the digital logic core. DCR should be bypassed with a capacitor to V2-. The DCR pin is not designed to power any external load.

V2+ - Positive Power 2, Pin 17

The V1+ and V2+ pins provide a positive supply voltage to the circuitry of the chip. These two pins should be decoupled as shown in the application block diagrams. V1+ and V2+ should be supplied from the same source voltage. For single-supply operation, these two voltages are nominally +5 V. For dual-supply operation, they are nominally +2.5 V.

V2- – Negative Power 2, Pin 18

The V1- and V2- pins provide a negative supply voltage to the circuitry of the chip. These two pins should be decoupled as shown in the application block diagrams. V1- and V2- should be supplied from the same source voltage. For single-supply operation, these two voltages are nominally 0 V (Ground). For dual-supply operation, they are nominally -2.5 V.

MCLK – Master Clock, Pin 19

The master clock pin (MCLK) is a multi-function pin. If tied low (MCLK = VLR), the on-chip oscillator will be enabled. If tied high (MCLK = VL), all clocks to the internal circuitry of the converter will stop. When MCLK is held high the internal oscillator will also be stopped. MCLK can also function as the input for an external CMOS-compatible clock that conforms to supply voltages on the VL and VLR pins.

VLR2, VLR, VL – Logic Interface Power/Return, Pins 14, 20, 21

VL and VLR are the supply voltages for the digital logic interface. VL and VLR can be configured with a wide range of common mode voltage. The following interface pins function from the VL/VLR supply: SMODE, CS, SCLK, SDO, RDY, SLEEP, CONV, RST, BP/UP, and MCLK.

SDO – Serial Data Output, Pin 22

SDO is the output pin for the serial output port. Data from this pin will be output at a rate determined by SCLK and in a format determined by the BP/UP pin. Data is output MSB first and advances to the next data bit on the rising edges of SCLK. SDO will be in a high impedance state when CS is high.



SCLK – Serial Clock Input/Output, Pin 23

The SMODE pin determines whether the SCLK signal is an input or an output signal. SCLK determines the rate at which data is clocked out of the SDO pin. If the converter is in SSC mode, the SCLK frequency will be determined by the master clock frequency of the converter (either MCLK or the internal oscillator). In SEC mode, the user determines the SCLK frequency.

If SMODE = VL (SSC Mode), SCLK will be in a high-impedance state when \overline{CS} is high.

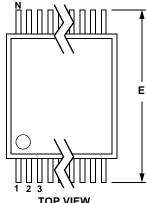
RDY – Ready, Pin 24

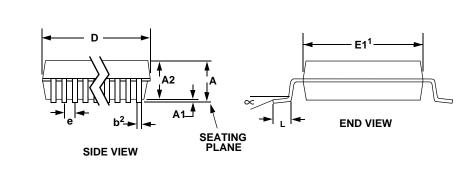
If CONV is low the converter will immediately start a conversion and RDY will remain high until the conversion is completed. At the end of any conversion RDY falls to indicate that a conversion word has been placed into the serial port. RDY will return high after all data bits are shifted out of the serial port or two master clock cycles before new data becomes available if the CS pin is inactive (high); or two master clock cycles before new data becomes available if the user holds \overline{CS} low but has not started reading the data from the converter when in SEC mode.



5. PACKAGE DIMENSIONS

24L SSOP PACKAGE DRAWING





TOP VIFW

		INCHES			MILLIMETERS		NOTE
DIM	MIN	NOM	MAX	MIN	NOM	MAX	
A			0.084			2.13	
A1	0.002	0.006	0.010	0.05	0.13	0.25	
A2	0.064	0.068	0.074	1.62	1.73	1.88	
b	0.009		0.015	0.22		0.38	2,3
D	0.311	0.323	0.335	7.90	8.20	8.50	1
E	0.291	0.307	0.323	7.40	7.80	8.20	
E1	0.197	0.209	0.220	5.00	5.30	5.60	1
е	0.022	0.026	0.030	0.55	0.65	0.75	
L	0.025	0.03	0.041	0.63	0.75	1.03	
~	0°	4°	8°	0°	4°	8°	

JEDEC #: MO-150

Controlling Dimension is Millimeters.

Notes: 1."D" and "E1" are reference datums and do not included mold flash or protrusions, but do include mold mismatch and are measured at the parting line, mold flash or protrusions shall not exceed 0.20 mm per side.

 2.Dimension "b" does not include dambar protrusion/intrusion. Allowable dambar protrusion shall be 0.13 mm total in excess of "b" dimension at maximum material condition. Dambar intrusion shall not reduce dimension "b" by more than 0.07 mm at least material condition.

3. These dimensions apply to the flat section of the lead between 0.10 and 0.25 mm from lead tips.



6. ORDERING INFORMATION

Model	Linearity	Temperature	Conversion Time	Throughput	Package
CS5566-ISZ	0.0005%	-40 to +85 °C	200 μs	5 kSps	24-pin SSOP

7. ENVIRONMENTAL, MANUFACTURING, & HANDLING INFORMATION

Model Number	Peak Reflow Temp	MSL Rating*	Max Floor Life	
CS5566-ISZ	260 °C	3	7 Days	

* MSL (Moisture Sensitivity Level) as specified by IPC/JEDEC J-STD-020.

8. REVISION HISTORY

Revision	Date	Changes	
PP1	MAR 2008	Preliminary release.	
PP2	MAY 2009	Corrected cross reference on page 22.	

Contacting Cirrus Logic Support

For all product questions and inquiries contact a Cirrus Logic Sales Representative.

To find the one nearest to you go to www.cirrus.com

IMPORTANT NOTICE

"Preliminary" product information describes products that are in production, but for which full characterization data is not yet available.

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